Low-Voltage 1.8/2.5/3.3V 16-Bit Buffer

With 26 Ω Series Resistors 3.6 V–Tolerant Inputs and Outputs (3–State, Inverting)

The 74VCX162240 is an advanced performance, inverting 16-bit buffer. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems.

When operating at 2.5 V (or 1.8 V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3 V busses. It is guaranteed to be over–voltage tolerant to 3.6 V.

The 74VCX162240 is nibble controlled with each nibble functioning identically, but independently. It is designed with 26 Ω series resistors in each of the outputs to reduce noise. The control pins may be tied together to obtain full 16-bit operation. The 3-state outputs are controlled by an Output Enable (\overline{OEn}) input for each nibble. When \overline{OEn} is LOW, the outputs are on. When \overline{OEn} is HIGH, the outputs are in the high impedance state.

- Designed for Low Voltage Operation: $V_{CC} = 1.65-3.6 \text{ V}$
- 3.6 V Tolerant Inputs and Outputs
- High Speed Operation: 3.3 ns max for 3.0 to 3.6 V

3.8 ns max for 2.3 to 2.7 V 7.6 ns max for 1.65 to 1.95 V

• Static Drive: ±12 mA Drive at 3.0 V

±8 mA Drive at 2.3 V ±3 mA Drive at 1.65 V

- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When V_{CC} = 0 V
- Near Zero Static Supply Current in All Three Logic States (20 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±300 mA @ 125°C
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V

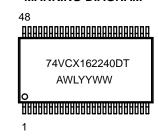


http://onsemi.com

MARKING DIAGRAM



TSSOP-48 DT SUFFIX CASE 1201



A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
74VCX162240DT	TSSOP	39 / Rail
74VCX162240DTR	TSSOP	2500 / Reel

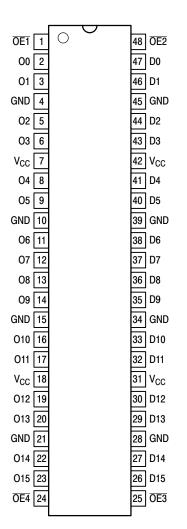
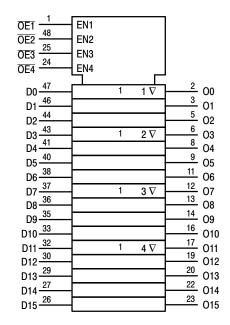


Figure 1. 48-Lead Pinout (Top View)

Figure 2. Logic Diagram



PIN NAMES

Pins	Function
OEn	Output Enable Inputs
D0-D15	Inputs
O0-O15	Outputs

OE1	D0:3	O0:3	OE2	D4:7	O4:7	OE3	D8:11	O8:11	OE4	D12:15	O12:15
L	L	L	L	L	L	L	L	L	L	L	L
L	Н	Н	L	Н	Н	L	Н	Н	L	Н	Н
Н	Х	Z	Н	Х	Z	Н	Х	Z	Н	Х	Z

 $H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for <math>I_{CC}$ reasons, DO NOT FLOAT Inputs

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +4.6$		V
V _O	DC Output Voltage	$-0.5 \le V_O \le +4.6$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1.; Outputs Active	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	$V_O > V_{CC}$	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

^{*} Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only	1.65 1.2	3.3	3.6 3.6	V
VI	Input Voltage	-0.3		3.6	V
V _O	Output Voltage (Active State) (3–State)	0 0		V _{CC} 3.6	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0V – 3.6V			-12	mA
I _{OL}	LOW Level Output Current, V _{CC} = 3.0V – 3.6V			12	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.3V - 2.7V			-8	mA
I _{OL}	LOW Level Output Current, V _{CC} = 2.3V - 2.7V			8	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 1.65V – 1.95V			-3	mA
l _{OL}	LOW Level Output Current, V _{CC} = 1.65V – 1.95V			3	mA
T _A	Operating Free–Air Temperature			+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V _{IN} from 0.8V to 2.0V, V _{CC} = 3.0V	0		10	ns/V

^{1.} I_O absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°0	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2.)	1.65V ≤ V _{CC} < 2.3V	0.65 x V _{CC}		V
		2.3V ≤ V _{CC} ≤ 2.7V	1.6		1
		2.7V < V _{CC} ≤ 3.6V	2.0		1
V _{IL}	LOW Level Input Voltage (Note 2.)	1.65V ≤ V _{CC} < 2.3V		0.35 x V _{CC}	V
		2.3V ≤ V _{CC} ≤ 2.7V		0.7	1
		2.7V < V _{CC} ≤ 3.6V		0.8	1
V _{OH}	HIGH Level Output Voltage	$1.65V \le V_{CC} \le 3.6V; I_{OH} = -100\mu A$	V _{CC} - 0.2		V
		V _{CC} = 1.65V; I _{OH} = -3mA	1.25		1
		$V_{CC} = 2.3V; I_{OH} = -4mA$	2.0		1
		V _{CC} = 2.3V; I _{OH} = -6mA	1.8		
		$V_{CC} = 2.3V; I_{OH} = -8mA$	1.7		
		V _{CC} = 2.7V; I _{OH} = -6mA	2.2		
		$V_{CC} = 3.0V; I_{OH} = -8mA$	2.4		1
		$V_{CC} = 3.0V; I_{OH} = -12mA$	2.2]
V _{OL}	LOW Level Output Voltage	$1.65V \le V_{CC} \le 3.6V; I_{OL} = 100\mu A$		0.2	V
		$V_{CC} = 1.65V; I_{OL} = 3mA$		0.3]
		$V_{CC} = 2.3V; I_{OL} = 6mA$		0.4]
		V _{CC} = 2.3V; I _{OL} = 8mA		0.6	
		$V_{CC} = 2.7V; I_{OL} = 6mA$		0.4]
		$V_{CC} = 3.0V; I_{OL} = 8mA$		0.55]
		V _{CC} = 3.0V; I _{OL} = 12mA		0.8	1
l _l	Input Leakage Current	$1.65V \le V_{CC} \le 3.6V; \ 0V \le V_{I} \le 3.6V$		±5.0	μΑ
l _{OZ}	3–State Output Current	$1.65V \le V_{CC} \le 3.6V$; $0V \le V_O \le 3.6V$; $V_I = V_{IH}$ or V_{IL}		±10	μА
I _{OFF}	Power–Off Leakage Current	$V_{CC} = 0V$; V_I or $V_O = 3.6V$		10	μА
I _{CC}	Quiescent Supply Current (Note 3.)	$1.65V \le V_{CC} \le 3.6V$; $V_I = GND \text{ or } V_{CC}$		20	μА
		$1.65V \le V_{CC} \le 3.6V; 3.6V \le V_I, V_O \le 3.6V$		±20	μА
ΔI_{CC}	Increase in I _{CC} per Input	$2.7V < V_{CC} \le 3.6V$; $V_{IH} = V_{CC} - 0.6V$		750	μΑ

^{2.} These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS (Note 4.; $t_R = t_F = 2.0$ ns; $C_L = 30$ pF; $R_L = 500\Omega$)

					Liı	mits			
					T _A = -40°	C to +85°C			
			V _{CC} = 3.0	V to 3.6V	V _{CC} = 2.3	V to 2.7V	V _{CC} = 1.6	5 to 1.95V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Input to Output	1	0.8 0.8	3.3 3.3	1.0 1.0	3.8 3.8	1.5 1.5	7.6 7.6	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	0.8 0.8	3.8 3.8	1.0 1.0	5.1 5.1	1.5 1.5	9.8 9.8	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	0.8 0.8	3.6 3.6	1.0 1.0	4.0 4.0	1.5 1.5	7.2 7.2	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 5.)			0.5 0.5		0.5 0.5		0.75 0.75	ns

^{4.} For C_L = 50pF, add approximately 300ps to the AC maximum specification.

^{3.} Outputs disabled or 3-state only.

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
V _{OLP}	Dynamic LOW Peak Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.15	V
	(Note 6.)	$V_{CC} = 2.5V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.25	
		$V_{CC} = 3.3V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.35	
V_{OLV}	Dynamic LOW Valley Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	-0.15	V
	(Note 6.)	$V_{CC} = 2.5V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	-0.25	
		$V_{CC} = 3.3V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	-0.35	
V _{OHV}	Dynamic HIGH Valley Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	1.55	V
	(Note 7.)	$V_{CC} = 2.5V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	2.05	
l		$V_{CC} = 3.3V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	2.65	

^{6.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

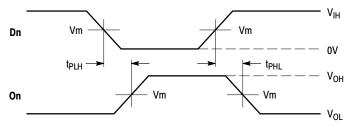
7. Number of outputs defined as "n". Measured with "n–1" outputs switching from HIGH–to–LOW or LOW–to–HIGH. The remaining output is

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	Note 8.	6	pF
C _{OUT}	Output Capacitance	Note 8.	7	pF
C _{PD}	Power Dissipation Capacitance	Note 8., 10MHz	20	pF

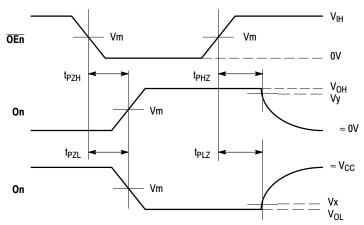
^{8.} V_{CC} = 1.8, 2.5 or 3.3V; V_I = 0V or V_{CC} .

measured in the HIGH state.



WAVEFORM 1 - PROPAGATION DELAYS

 t_R = t_F = 2.0ns, 10% to 90%; f = 1MHz; t_W = 500ns

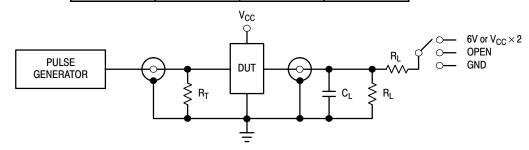


WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

 t_R = t_F = 2.0ns, 10% to 90%; f = 1MHz; t_W = 500ns

Figure 3. AC Waveforms

		V _{CC}		
Symbol	3.3V ±0.3V	2.5V ±0.2V	1.8V ±0.15V	
V _{IH}	2.7V	V _{CC}	V _{CC}	
V _m	1.5V	V _{CC} /2	V _{CC} /2	
V _x	V _{OL} + 0.3V	V _{OL} + 0.15V	V _{OL} + 0.15V	
V _y	V _{OH} – 0.3V	V _{OH} – 0.15V	V _{OH} – 0.15V	

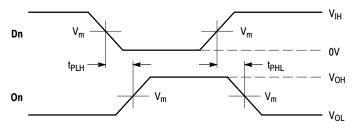


TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$; $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$; 1.8 $\pm 0.15V$
t _{PZH} , t _{PHZ}	GND

 C_L = 30pF or equivalent (Includes jig and probe capacitance) R_L = 500Ω or equivalent

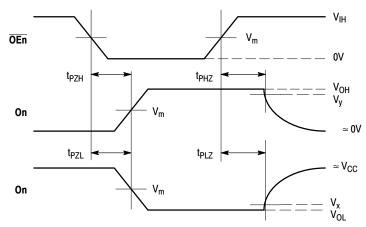
 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit



WAVEFORM 3 - PROPAGATION DELAYS

 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1MHz; $t_W = 500$ ns

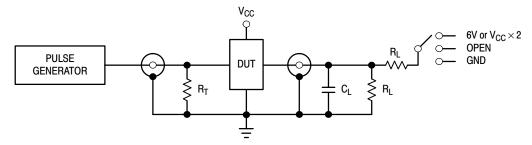


WAVEFORM 4 - OUTPUT ENABLE AND DISABLE TIMES

 t_R = t_F = 2.0ns, 10% to 90%; f = 1MHz; t_W = 500ns

Figure 5. AC Waveforms

	V _{CC}			
Symbol	3.3V ±0.3V	2.7V		
V _{IH}	2.7V	2.7V		
V _m	1.5V	1.5V		
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V		
V _y	V _{OH} – 0.3V	V _{OH} – 0.3V		



TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at V_{CC} = 3.3 ±0.3V; $V_{CC} \times 2$ at V_{CC} = 2.5 ±0.2V; 1.8 ±0.15V
t _{PZH} , t _{PHZ}	GND

C_L = 50pF or equivalent (Includes jig and probe capacitance)

 $R_L = 500\Omega$ or equivalent $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 6. Test Circuit

AC CHARACTERISTICS ($t_R = t_F = 2.0 \text{ns}$; $C_L = 50 \text{pF}$; $R_L = 500 \Omega$)

			Limits				
				T _A = −40°C	c to +85°C		
			V _{CC} = 3.0	OV to 3.6V	V _{CC} =	= 2.7V	1
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
t _{PLH} t _{PHL}	Propagation Delay Input to Output	3	1.0 1.0	4.2 4.2		4.7 4.7	ns
t _{PZH}	Output Enable Time to High and Low Level	4	1.0 1.0	5.6 5.6		6.7 6.7	ns
t _{PHZ}	Output Disable Time From High and Low Level	4	1.0 1.0	5.5 5.5		5.7 5.7	ns
toshl toslh	Output-to-Output Skew (Note 9.)			0.5 0.5		0.5 0.5	ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

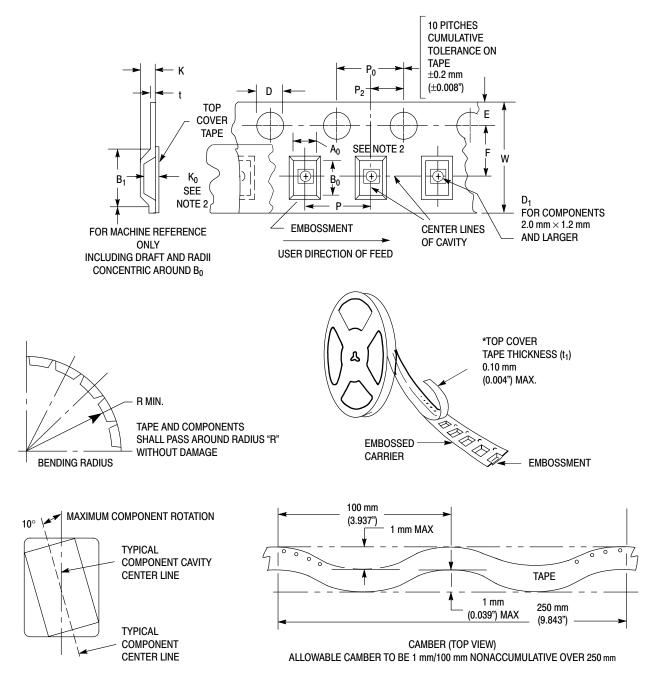


Figure 7. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 1 and 2)

Tape Size	B ₁ Max	D	D ₁	E	F	к	Р	P ₀	P ₂	R	Т	w
24mm	20.1mm (0.791")	1.5 + 0.1mm -0.0 (0.059 +0.004" -0.0)	1.5mm Min (0.060")	1.75 ±0.1 mm (0.069 ±0.004")	11.5 ±0.10 mm (0.453 ±0.004")	11.9 mm Max (0.468")	16.0 ±0.1 mm (0.63 ±0.004")	4.0 ±0.1 mm (0.157 ±0.004")	2.0 ±0.1 mm (0.079 ±0.004")	30 mm (1.18")	0.6 mm (0.024")	24.3 mm (0.957")

- 1. Metric Dimensions Govern-English are in parentheses for reference only.
- 2. A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

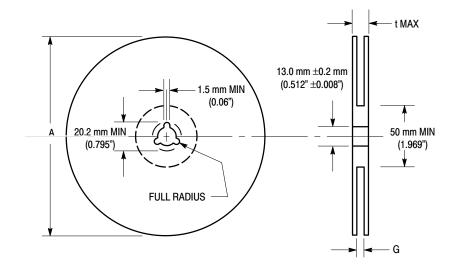


Figure 8. Reel Dimensions

REEL DIMENSIONS

Tape Size	A Max	G	t Max
24 mm	360 mm	24.4 mm + 2.0 mm, -0.0	30.4 mm
	(14.173")	(0.961" + 0.078", -0.00)	(1.197")

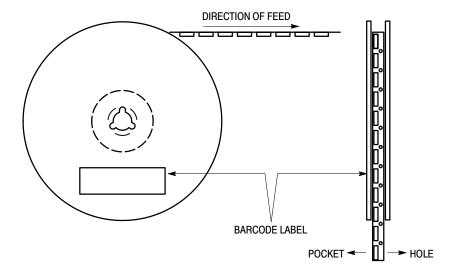


Figure 9. Reel Winding Direction

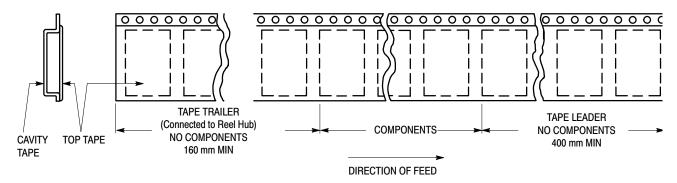


Figure 10. Tape Ends for Finished Goods

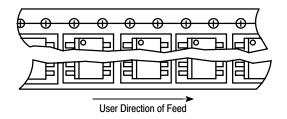
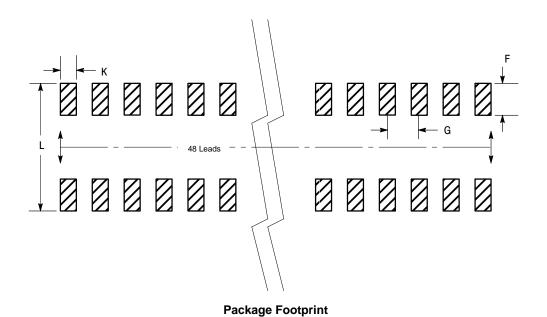


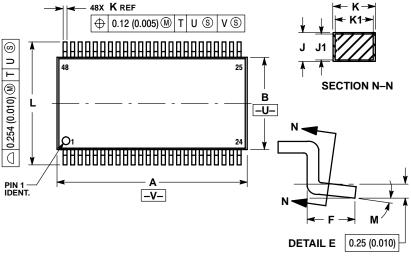
Figure 11. Reel Configuration



PACKAGE DIMENSIONS

TSSOP DT SUFFIX CASE 1201-01

ISSUE A



- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- T 14.5WI, 1962.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE
 MOLD FLASH, PROTRUSIONS OR GATE
 BURRS. MOLD FLASH OR GATE BURRS
- SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN
 EXCESS OF THE K DIMENSION AT MAXIMUM
 MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSIONS A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	12.40	12.60	0.488	0.496	
В	6.00	6.20	0.236	0.244	
C		1.10		0.043	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.50	BSC	0.0197 BSC		
Н	0.37		0.015		
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.17	0.27	0.007	0.011	
K1	0.17	0.23	0.007	0.009	
L	7.95	8.25	0.313	0.325	
M	0 °	8 °	0 °	8 °	

D√C	- W
○ 0.076 (0.003) ↑ ↑ ↑ ← C → C → C → C → C → C → C → C → C → C	 DETAIL E

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Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-0031

Phone: 81-3-5740-2745 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local Sales Representative.